



U.S. PATENT APPLICATION ASSIGNMENT  
SOLE OR JOINT INVENTORS  
EXECUTED OUTSIDE U.S.A.

Attorney's  
Docket No.: \_\_\_\_\_

WHEREAS, I (We), 1) KWOK Cheuk Sang and 2) LEE Kit Yee both  
c/o The Hong Kong Polytechnic University, Hung Hom, Kowloon, Hong Kong

as assignor(s), have invented certain improvements in  
Microdensitometer

for which an application for United States Letters Patent  
has been executed by me (us) of even date herewith  
and whereas

The Hong Kong Polytechnic University of Hung Hom, Kowloon, Hong Kong.

as assignee, is desirous of acquiring all right, title and in-  
terest for the United States in and to said invention and any  
U.S. Patent that may be granted therefor.

NOW, THEREFORE, in consideration of One Dollar (\$1.00)  
and other good and valuable consideration, the receipt of which  
is hereby acknowledged, I (We), as assignor(s), hereby sell,  
assign and set over to said assignee the entire right, title and  
interest for the United States in and to said invention and the  
aforesaid United States application for Patent, all original,  
divisional, continuation, substitute or reissue applications and  
patents applied for or granted therefor in the United States in-  
cluding all rights of priority from the filing of said applica-  
tion, and the Commissioner of Patents is hereby authorized and  
requested to issue all patents on said invention or resulting  
therefrom to said assignee herein, as assignee of the entire  
interest therein; and the undersigned for myself (ourselves) and  
my (our) legal representatives, heirs and assigns do hereby agree  
and covenant without further remuneration, to execute and deliver  
all divisional, continuation, reissue and other applications for  
Patent on said invention and all assignments thereof to said  
assignee or its assigns, to communicate to said assignee or its  
representatives all facts known to the undersigned respecting  
said invention, whenever requested, to testify in any interfer-  
ences or other legal proceedings in which any of said applica-  
tions or patents may become involved, to sign all lawful papers,  
make all rightful oaths, and to do generally everything necessary  
to aid said assignee, its successors, assigns and nominees to  
obtain patent protection for said invention in the United States,  
the expenses incident to said applications to be borne and paid  
by said assignee.

Dated: July 20, 2003 Assignor :   
1) KWOK Cheuk Sang 2) LEE KIT Yee

Witnesses: (1) 

(2) \_\_\_\_\_

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obtain patent protection for said invention in the United States,  
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by said assignee.

Dated: July 22, 2003

Assignor :

1) KWOK Cheuk Sang      2) LEE KIT Yee

Witnesses: (1)

(2)

**PATENT**